

PNP -100mA -50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value
V _{CEO}	-50V
I _C	-100mA
R ₁	4.7kΩ

Features

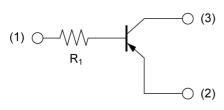
- 1) Built-In Biasing Resistor
- 2) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary NPN Types: DTC143T series

Application

INVERTER, INTERFACE, DRIVER

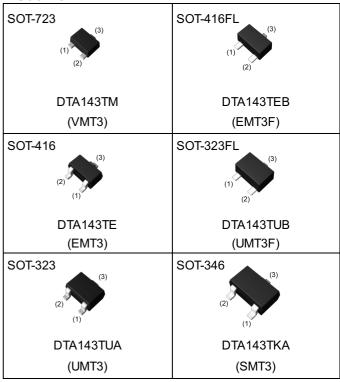
Inner circuit

DTA143TM/ DTA143TEB/ DTA143TUB

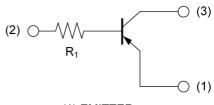


- (1) BASE
- (2) EMITTER
- (3) COLLECTOR

Outline



DTA143TE/ DTA143TUA/ DTA143TKA



- (1) EMITTER
- (2) BASE
- (3) COLLECTOR

Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTA143TM	SOT-723	1212	T2L	180	8	8000	93
DTA143TEB	SOT-416FL	1616	TL	180	8	3000	93
DTA143TE	SOT-416	1616	TL	180	8	3000	93
DTA143TUB	SOT-323FL	2021	TL	180	8	3000	93
DTA143TUA	SOT-323	2021	T106	180	8	3000	93
DTA143TKA	SOT-346	2928	T146	180	8	3000	93

● Absolute maximum ratings (T_a = 25°C)

Pa	arameter	Symbol	Values	Unit
Collector-base voltage	V_{CBO}	-50	V	
Collector-emitter voltage			-50	V
Emitter-base voltage			-5	V
Collector current			-100	mA
	DTA143TM		150	
DTA143TEB			150	
Davie a discipation	DTA143TE	P _D *1	150	mW
Power dissipation	DTA143TUB	P _D .	200	
	DTA143TUA		200	
DTA143TKA			200	
Junction temperature		T _j	150	°C
Range of storage temperar	ture	T _{stg}	-55 to +150	°C

●Electrical characteristics (T_a = 25°C)

Davanastan	Currente ed	Conditions	Values			Lleit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = -50μA	-50	-	-	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = -1mA	-50	-	-	V
Emitter-base breakdown voltage	BV _{EBO}	I _E = -50μA	-5	-	-	V
Collector cut-off current	I _{CBO}	V _{CB} = -50V	-	1	-500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = -4V	-	-	-500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -5mA, I_B = -0.25mA$	-	-	-300	mV
DC current gain	h _{FE}	$V_{CE} = -5V, I_{C} = -1mA$	100	250	600	-
Input resistance	R ₁	-	3.29	4.7	6.11	kΩ
Transition frequency	f _T *2	V _{CE} = -10V, I _E = 5mA, f = 100MHz	-	250	-	MHz

^{*1} Each terminal mounted on a reference land.

^{*2} Characteristics of built-in transistor

● Electrical characteristic curves(Ta=25°C)

Fig.1 Grounded emitter propagation characteristics

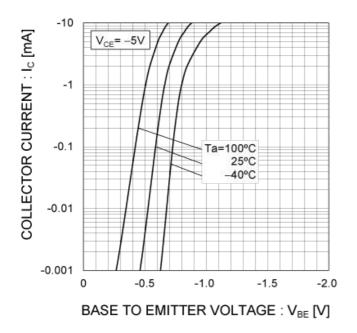


Fig.2 Grounded emitter output characteristics

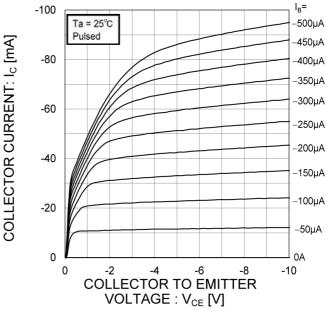


Fig.3 DC Current gain vs. Collector Current

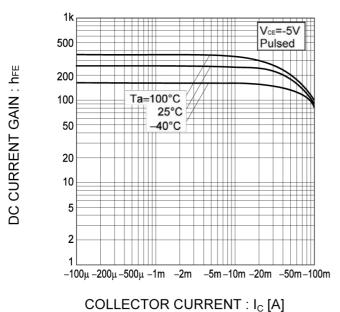
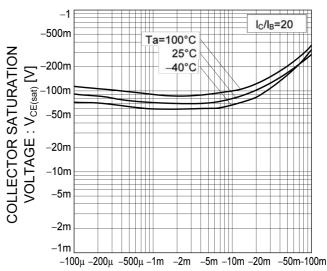
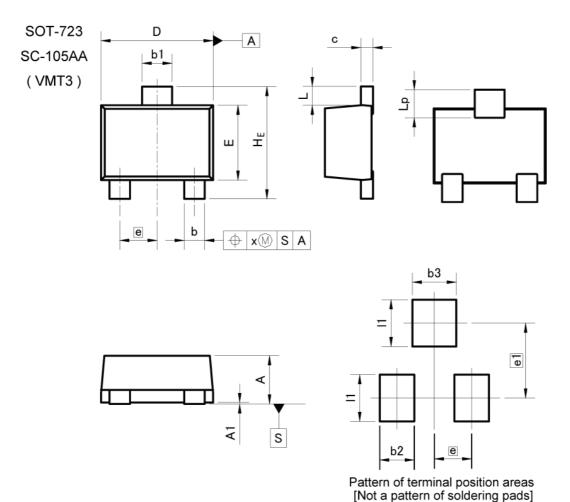


Fig.4 Collector-emitter saturation voltage vs. Collector Current



COLLECTOR CURRENT : I_C [A]



MILIMETERS INCHES DIM MIN MIN MAX MAX A 0.45 0.55 0.018 0.022 A1 0.00 0.10 0.000 0.004 b 0.17 0.27 0.007 0.011 0.27 0.37 b1 0.011 0.015 0.08 0.18 0.003 0.007 С D 1.10 1.30 0.043 0.051 0.70 Ε 0.90 0.028 0.035 0.40 е HE 1.10 1.30 0.043 0.051 0.10 0.30 0.004 0.012 L 0.20 0.008 0.40 0.016 Lр

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2	<u> </u>	0.37	544	0.015
b3	223	0.47	922	0.019
e1	0.80		0.0	031
11	5 98	0.50	250	0.020

0.10

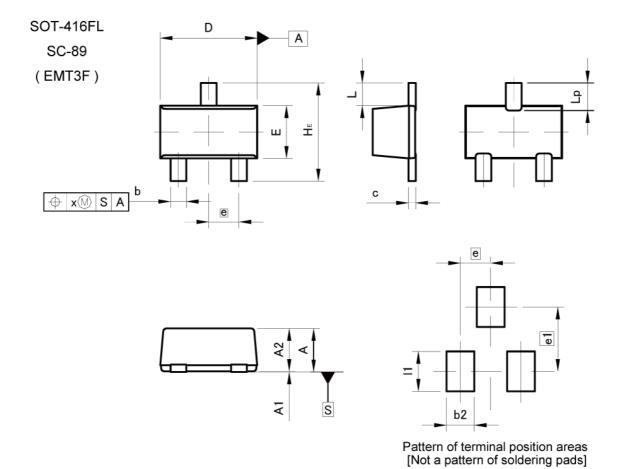
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Dimension in mm/inches

X



0.004

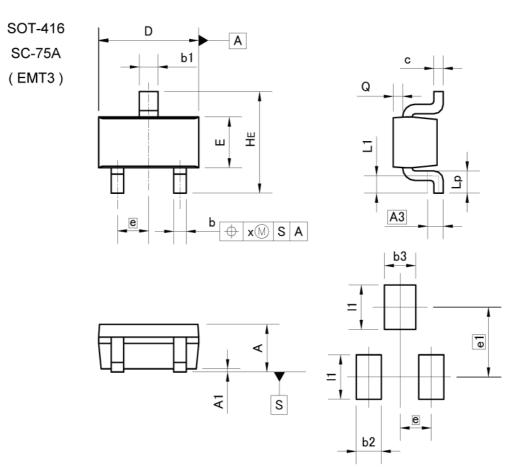


DIM -	MILIM	ETERS	INCHES	
DIM [MIN	MAX	MIN	MAX
Α	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
A2	0.60	0.80	0.024	0.031
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.50 0.020		20	
HE	1.50	1.70	0.059	0.067
L	0.37		0.0	15
Lp	0.35	0.55	0.014	0.022
х		0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	= 1	0.46	_	0.018
e1		1.05		0.041
11	#	0.65	=	0.026

Dimension in mm/inches





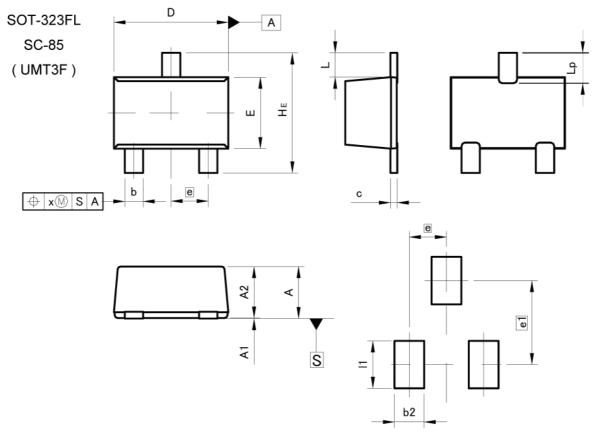
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INCHES	
DIM [MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10	#3	0.004	S #
Lp	0.15		0.006	255
Q	0.05	0.25	0.002	0.010
х	2 7	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	2044	0.40	-	0.016
b3	10 41	0.50	÷(0.020
e1	1.	1.10		043
11		0.70	-	0.028

Dimension in mm/inches





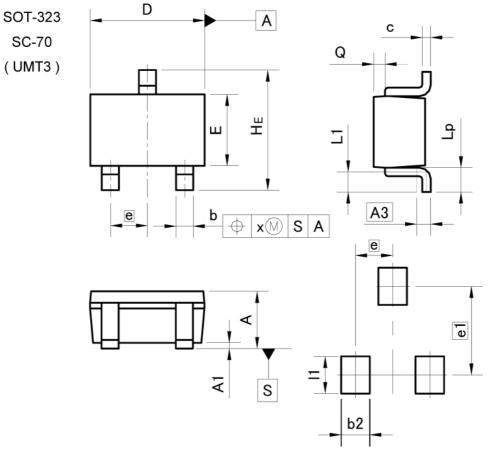
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
С	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	0.65 0.0		26
HE	2.00	2.20	0.079	0.087
L	0.4	25	0.0	17
Lp	0.43	0.63	0.017	0.025
х	==:	0.10	-	0.004

DIM	MILIME	TERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2	- s	0.52	-	0.020
e1	1.47		0.0	58
11	 k	0.83	-	0.033

Dimension in mm/inches





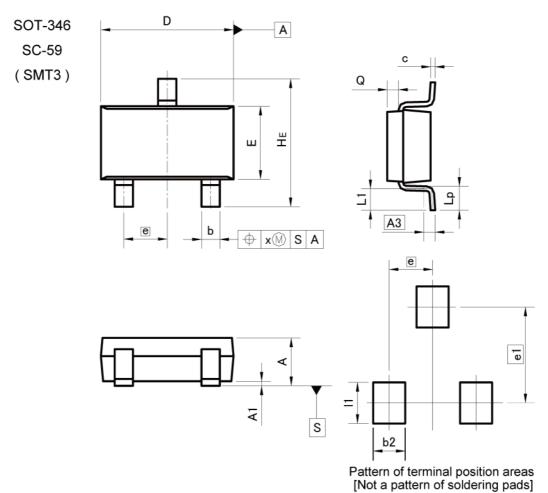
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INC	HES
DIM [MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.2	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	35	0.026	
HE	2.00	2.20	0.079	0.087
L1	0.10	0.40	0.004	0.016
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	=	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	<u>64</u> 9	0.50	<u>~</u>	0.020
e1	1.55		0.061	
11	-	0.65	1000	0.026

Dimension in mm/inches





[Not a pattern of soldering pads]

DIM MILIMETERS INCHES

MIN MAX MIN MAX

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	-,	0.10	4.5	0.004
У	-0.	0.10	9 7.	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-2	0.60	×=	0.024
e1	2.10		0.083	
11	-8	0.90	(=	0.035

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSIII	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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